

Type IIIB

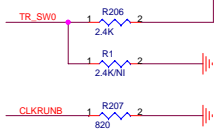
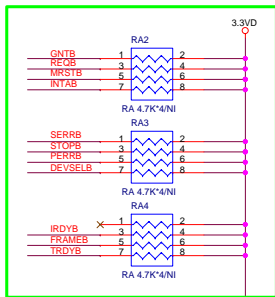
RFTXDIS#	>>>RFTXDIS#	4	LD1P_ACT	<<<LD1P_ACT	4
GNTB	>>>GNTB	4	LD2P_24G	<<<LD2P_24G	4
REQB	<<<REQB	4	LD2_YN5	<<<LD2_YN5	4
MRSTB	>>>MRSTB	4	INTAB	<<<INTAB	4
AD[0..31]	>>>AD[0..31]	4	IDSEL	>>>IDSEL	4
CBE0B	>>>CBE0B	4	STOPB	>>>STOPB	4
CBE1B	>>>CBE1B	4	DEVSELB	>>>DEVSELB	4
CBE2B	>>>CBE2B	4	PERRB	>>>PERRB	4
CBE3B	>>>CBE3B	4	FRAMEB	>>>FRAMEB	4
PAR	>>>PAR	4	SERRB	<<<SERRB	4
TRDYB	>>>TRDYB	4	CCLK	>>>CCLK	4
IRDYB	>>>IRDYB	4	CLKRUNB	>>>CLKRUNB	4



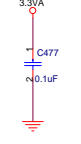
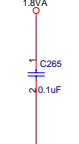
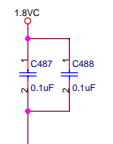
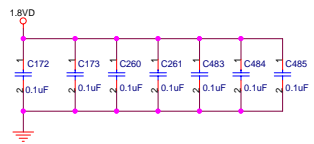
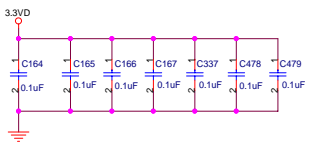
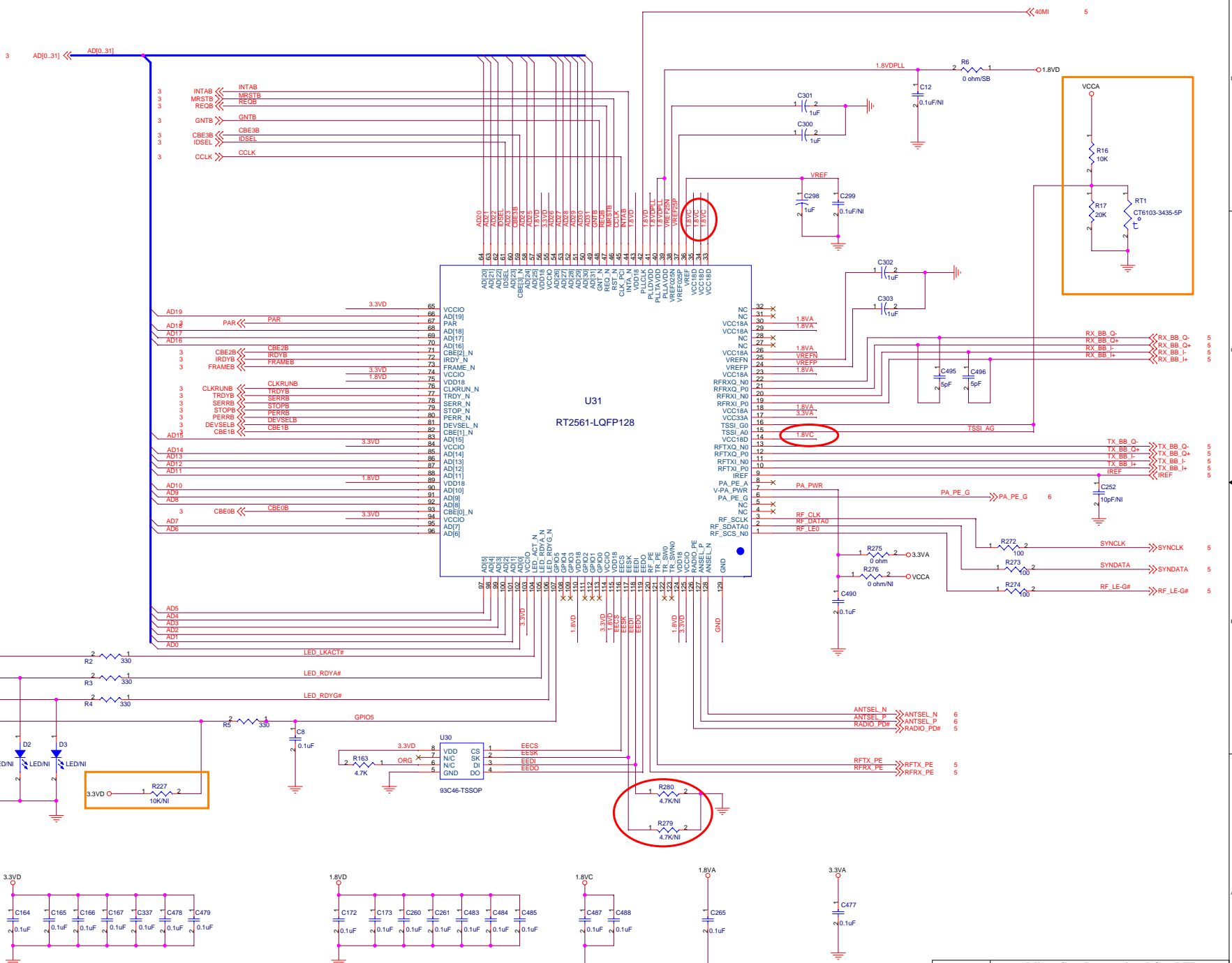
**Micro-Star International Co., LTD.**

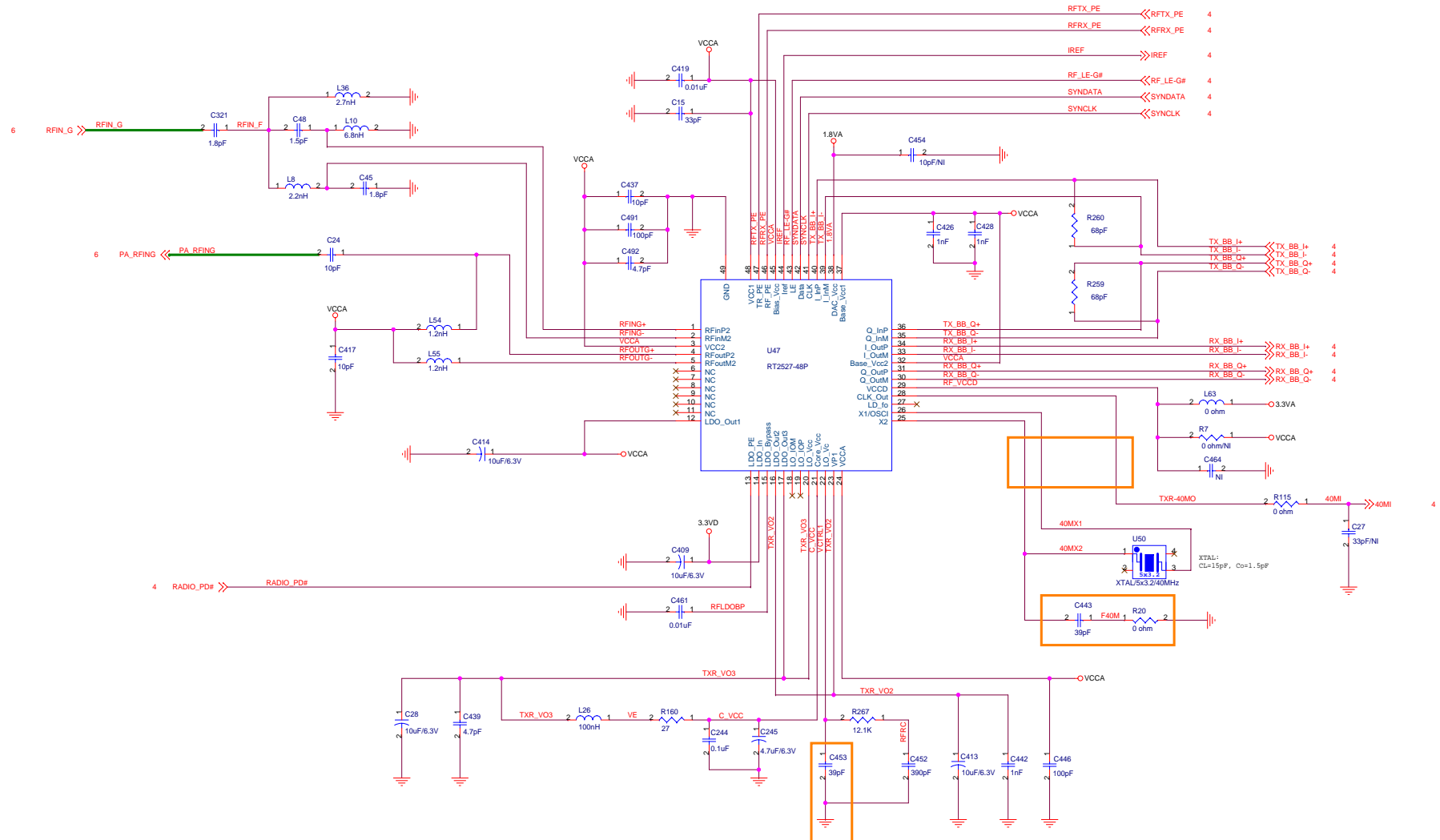
**Mini PCI Interface and Power**

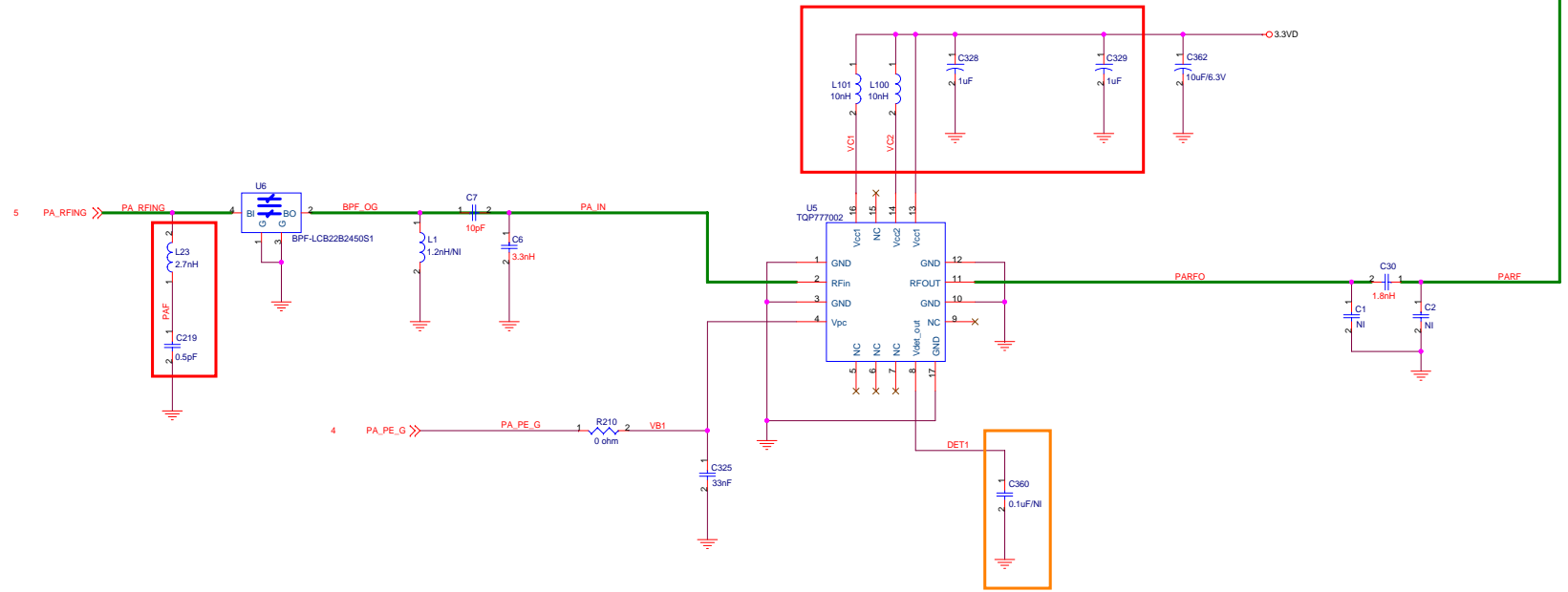
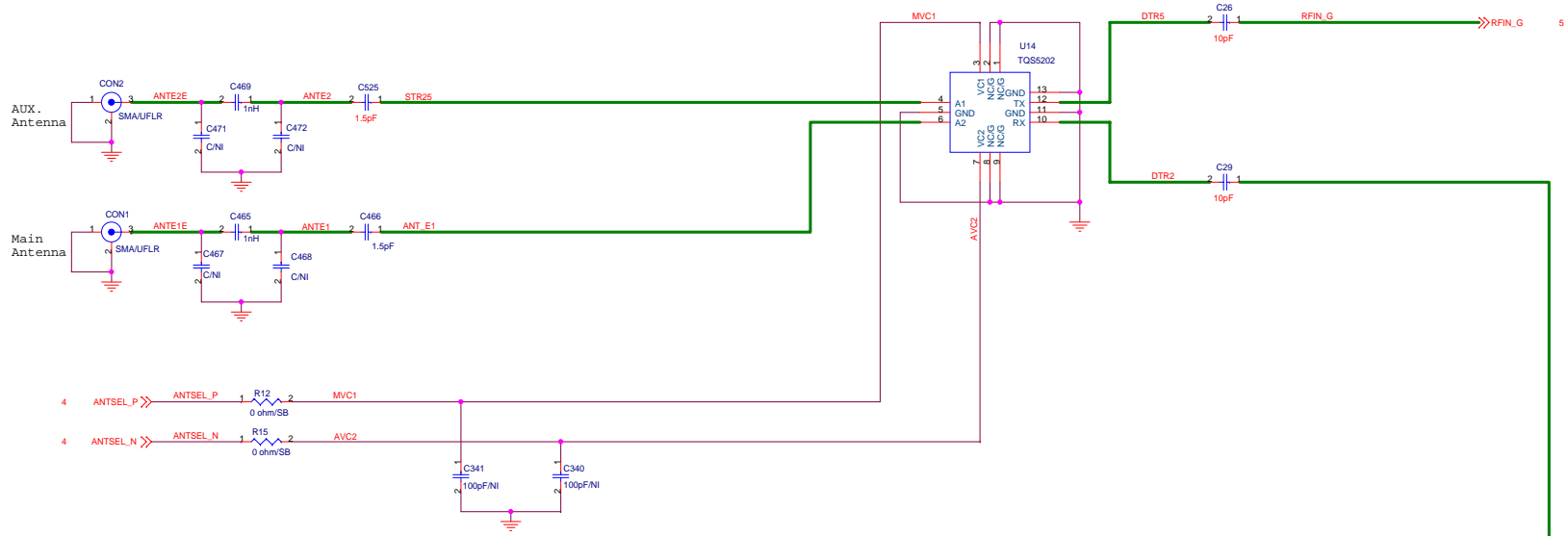
Size B	Document Number	Rev 0A
	<b>MS6833B</b>	
Date:	Tuesday, July 05, 2005	Sheet 3 of 8

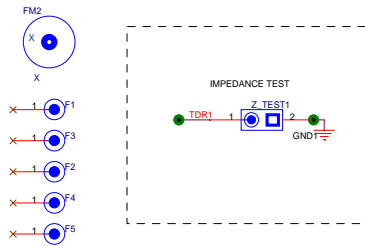
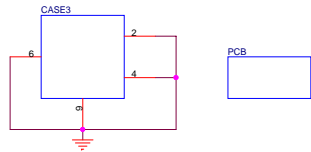


Mode	Install	Not Install
93C46	R206	R1
93C66	R1	R206









Mini-PCI PCB Layer Stack-Up

	Material	Thickness
	Solder mask	0.4 mil
(TOP)	LAYER 1 1/2 OZ Cu + Gold Plating	1.6 mil
	PrePeg FR4 (1506)	12 mil
(Ground)	LAYER 2 1 OZ Cu	1.6 mil
	Core FR4	7 mil
(Power)	LAYER 3 1 OZ Cu	1.6 mil
	PrePeg FR4 (1506)	12 mil
(Bottom)	LAYER 4 1/2 OZ Cu + Gold Plating	1.6 mil
	Solder mask	0.4 mil

( Finished Total Thickness: 39+-4 mil )

Dielectric Constant: 4.3  
50-ohm Co-Planar Waveguide: 16 mil Line Width, 10 mil Gap Width